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SECTION 1. GENERAL

SERVICING PRECAUTIONS NOTES REGARDING HANDLING OF THE PICK-UP

1. Notes for transport and storage

1) The pick-up should always be left in its conductive bag until immediately prior to use.

2) The pick-up should never be subjected to external pressure or impact.

Storage in conductive bag



- 1) The pick-up incorporates a strong magnet, and so should never be brought close to magnetic materials.
- 2) The pick-up should always be handled correctly and carefully, taking care to avoid external pressure and impact. If it is subjected to strong pressure or impact, the result may be an operational malfunction and/or damage to the printed-circuit board.
- 3) Each and every pick-up is already individually adjusted to a high degree of precision, and for that reason the adjustment point and installation screws should absolutely never be touched.
- 4) Laser beams may damage the eyes! Absolutely never permit laser beams to enter the eyes! Also NEVER switch ON the power to the laser output part (lens, etc.) of the pick-up if it is damaged.

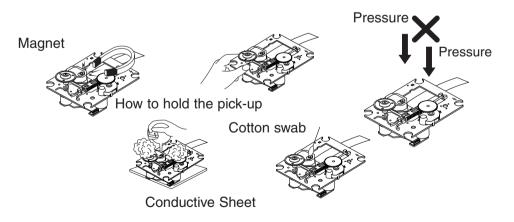


NEVER look directly at the laser beam, and don't let contact fingers or other exposed skin.

Drop impact

5) Cleaning the lens surface

If there is dust on the lens surface, the dust should be cleaned away by using an air bush (such as used for camera lens). The lens is held by a delicate spring. When cleaning the lens surface, therefore, a cotton swab should be used, taking care not to distort this.



6) Never attempt to disassemble the pick-up.

Spring by excess pressure. If the lens is extremely dirty, apply isopropyl alcohol to the cotton swab. (Do not use any other liquid cleaners, because they will damage the lens.) Take care not to use too much of this alcohol on the swab, and do not allow the alcohol to get inside the pick-up.

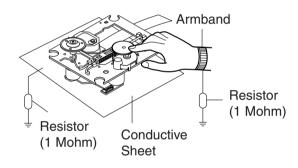
NOTES REGARDING COMPACT DISC PLAYER REPAIRS

1. Preparations

- 1) Compact disc players incorporate a great many ICs as well as the pick-up (laser diode). These components are sensitive to, and easily affected by, static electricity. If such static electricity is high voltage, components can be damaged, and for that reason components should be handled with care.
- 2) The pick-up is composed of many optical components and other high-precision components. Care must be taken, therefore, to avoid repair or storage where the temperature of humidity is high, where strong magnetism is present, or where there is excessive dust.

2. Notes for repair

- 1) Before replacing a component part, first disconnect the power supply lead wire from the unit
- 2) All equipment, measuring instruments and tools must be grounded.
- 3) The workbench should be covered with a conductive sheet and grounded. When removing the laser pick-up from its conductive bag, do not place the pick-up on the bag. (This is because there is the possibility of damage by static electricity.)
- 4) To prevent AC leakage, the metal part of the soldering iron should be grounded.
- 5) Workers should be grounded by an armband (1M Ω)
- 6) Care should be taken not to permit the laser pick-up to come in contact with clothing, in order to prevent static electricity changes in the clothing to escape from the armband.
- 7) The laser beam from the pick-up should NEVER be directly facing the eyes or bare skin.



□ ESD PRECAUTIONS

Electrostatically Sensitive Devices (ESD)

Some semiconductor (solid state) devices can be damaged easily by static electricity. Such components commonly are called Electrostatically Sensitive Devices (ESD). Examples of typical ESD devices are integrated circuits and some field-effect transistors and semiconductor chip components. The following techniques should be used to help reduce the incidence of component damage caused by static electricity.

- 1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed for potential shock reasons prior to applying power to the unit under test.
- 2. After removing an electrical assembly equipped with ESD devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
- 3. Use only a grounded-tip soldering iron to solder or unsolder ESD devices.
- 4. Use only an anti-static solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ESD devices.
- 5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ESD devices.
- 6. Do not remove a replacement ESD device from its protective package until immediately before you are ready to install it. (Most replacement ESD devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive materials).
- 7. Immediately before removing the protective material from the leads of a replacement ESD device, touch the protective material to the chassis or circuit assembly into which the device will by installed.

CAUTION : BE SURE NO POWER IS APPLIED TO THE CHASSIS OR CIRCUIT, AND OBSERVE ALL OTHER SAFETY PRECAUTIONS.

8. Minimize bodily motions when handing unpackaged replacement ESD devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ESD device).

CAUTION. GRAPHIC SYMBOLS



THE LIGHTNING FLASH WITH APROWHEAD SYMBOL. WITHIN AN EQUILATERAL TRIANGLE, IS INTENDED TO ALERT THE SERVICE PERSONNEL TO THE PRESENCE OF UNINSULATED "DANGER-OUS VOLTAGE" THAT MAY BE OF SUFFICIENT MAGNITUDE TO CONSTITUTE A RISK OF ELECTRIC SHOCK.



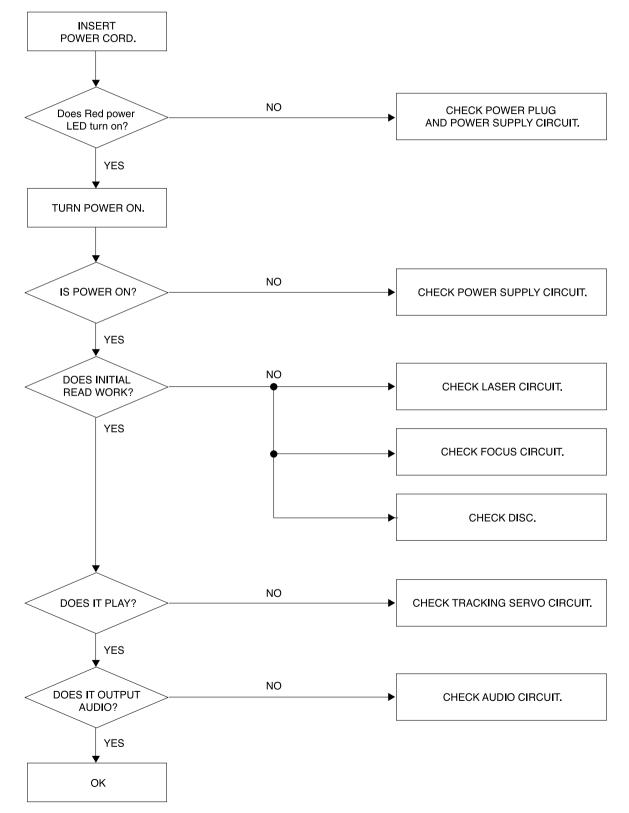
THE EXCLAMATION POINT WITHIN AN EQUILATERAL TRIANGLE IS INTENDED TO ALERT THE SERVICE PERSONNEL TO THE PRESENCE OF IMPORTANT SAFETY INFORMATION IN SERVICE LITERATURE.

MEMO

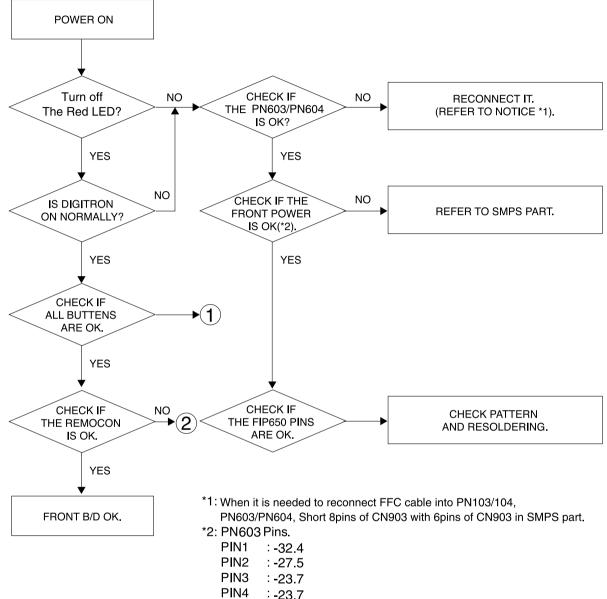
SECTION 2. AUDIO PART

□ AUDIO TROUBLESHOOTING GUIDE

1. POWER SUPPLY CIRCUIT

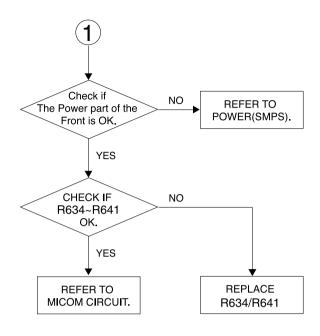


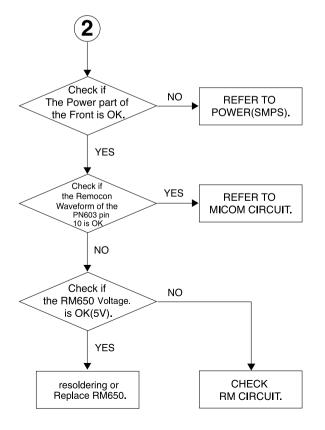
2. FRONT CIRCUIT (1/2)



PIN4 : -23.7 PIN11 : -5.0

3. FRONT CIRCUIT (2/2)

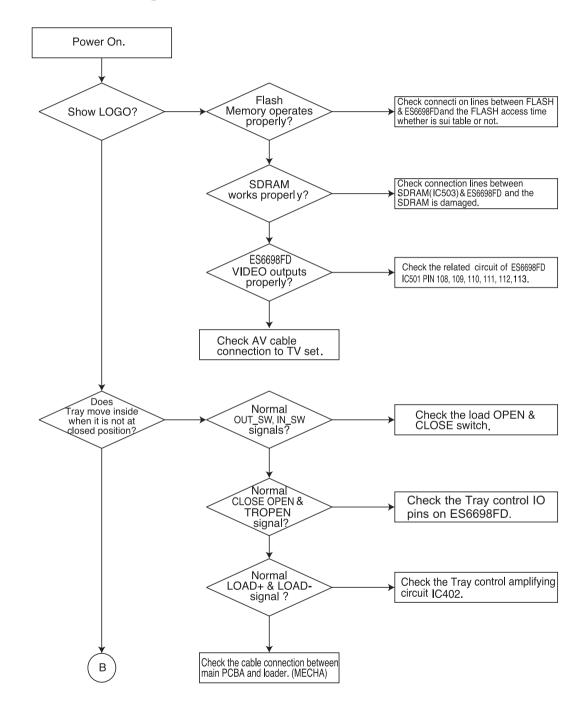


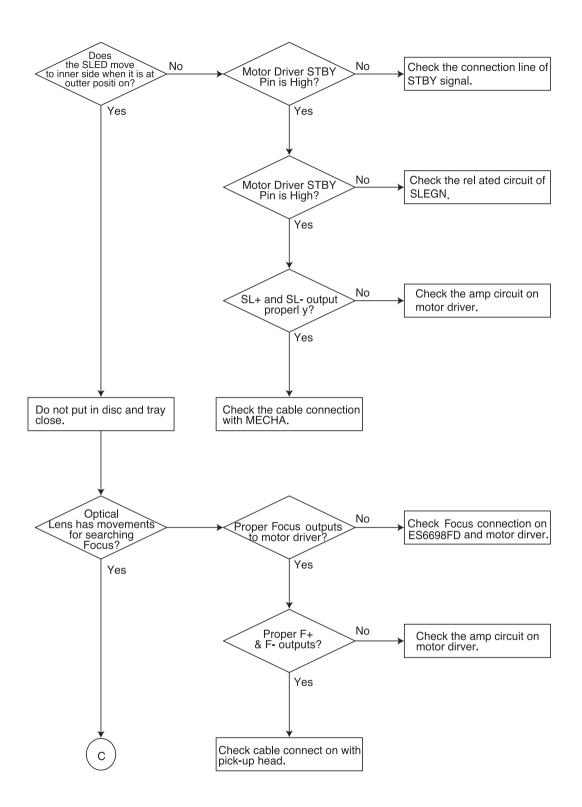


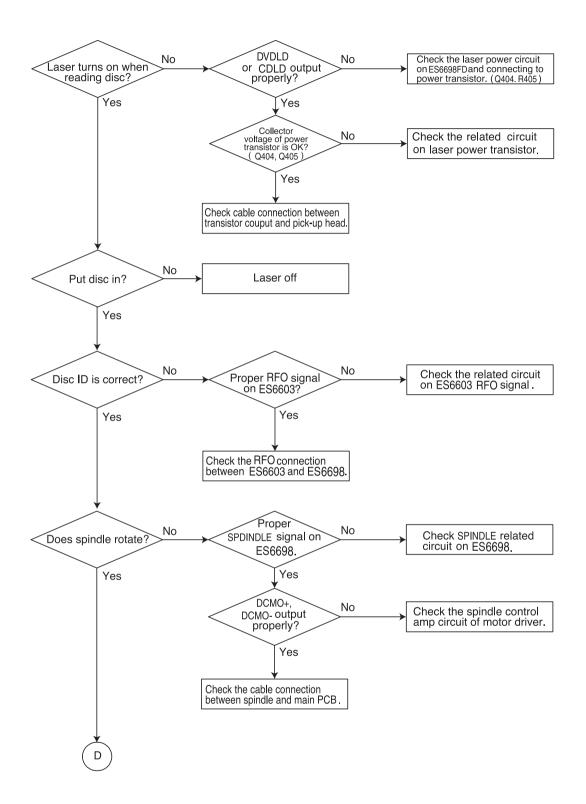
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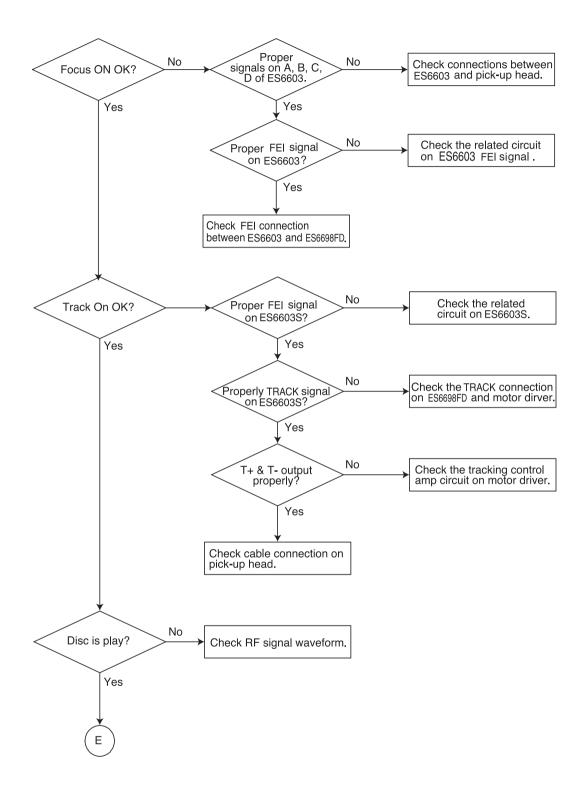
SECTION 3. DVD PART TROUBLESHOOTING GUIDE

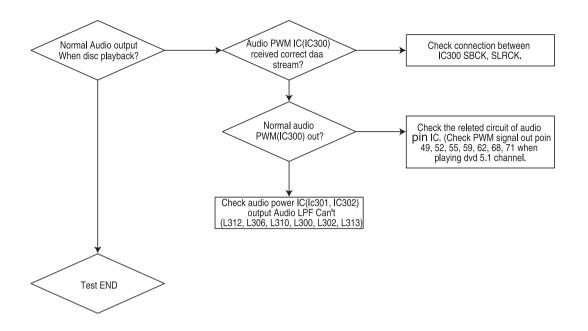
1. Test & debug flow







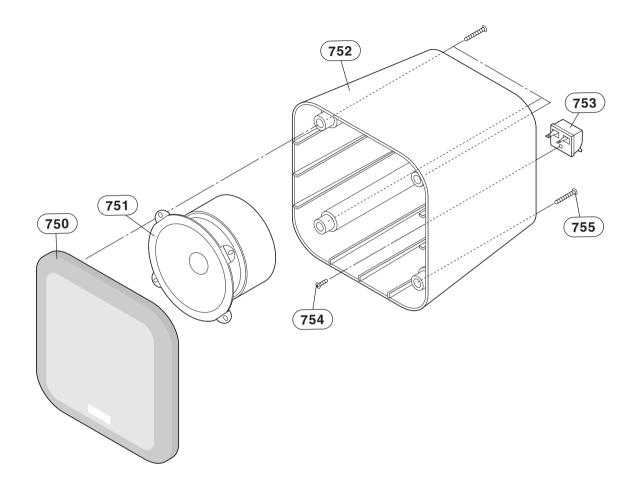




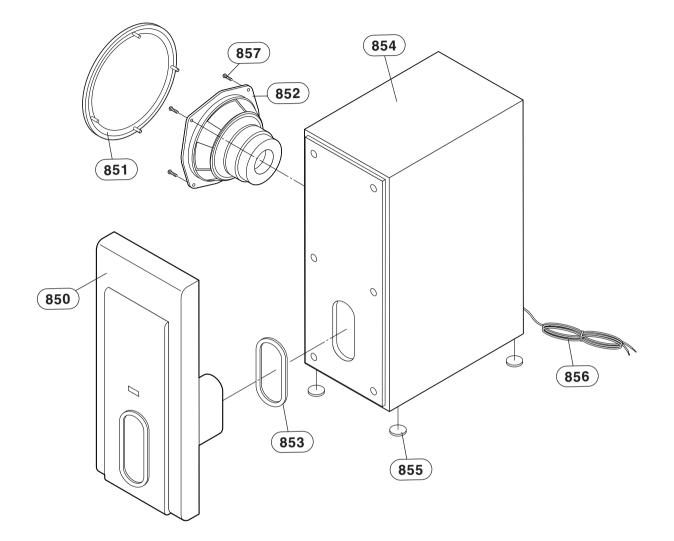
MEMO

SECTION 5. SPEAKER SECTION

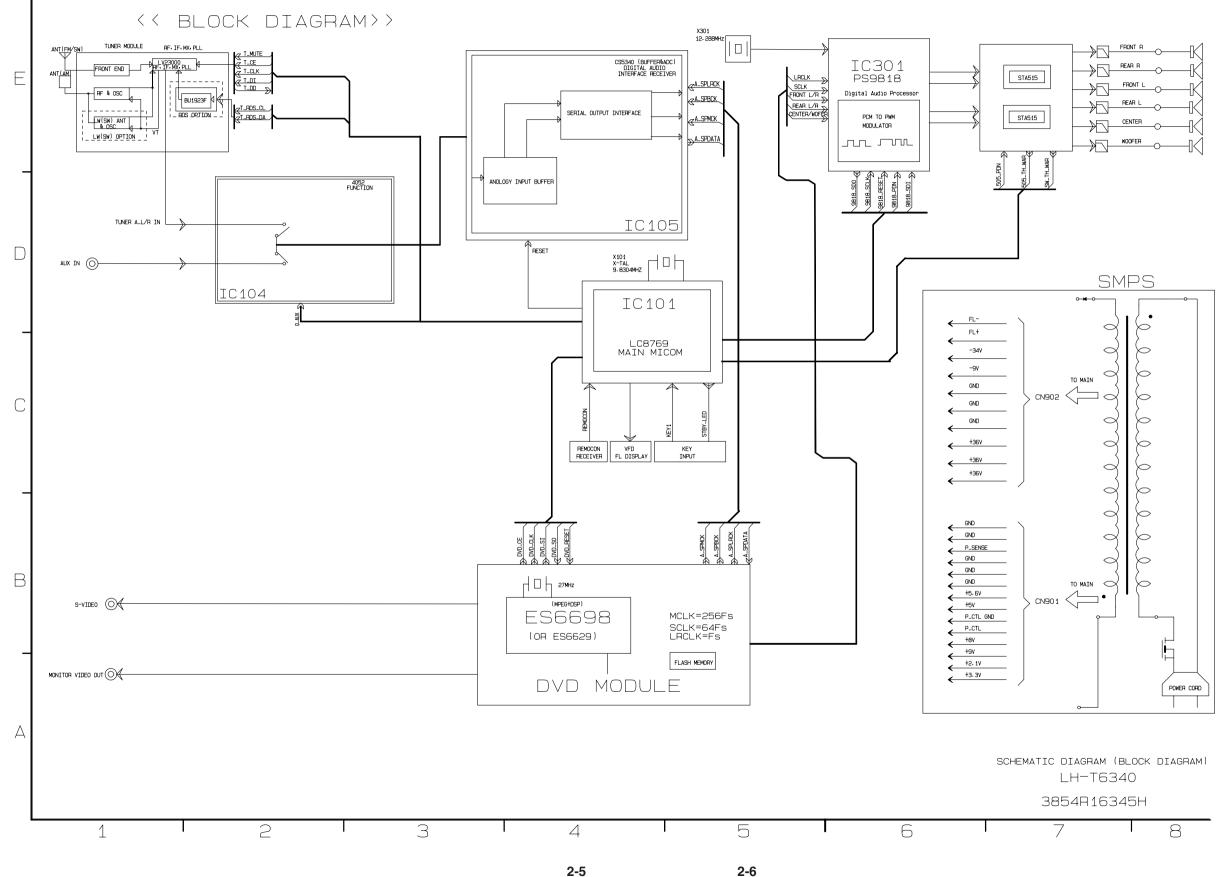
□ MODEL : LHS-T6340T



□ MODEL : LHS-T6340W

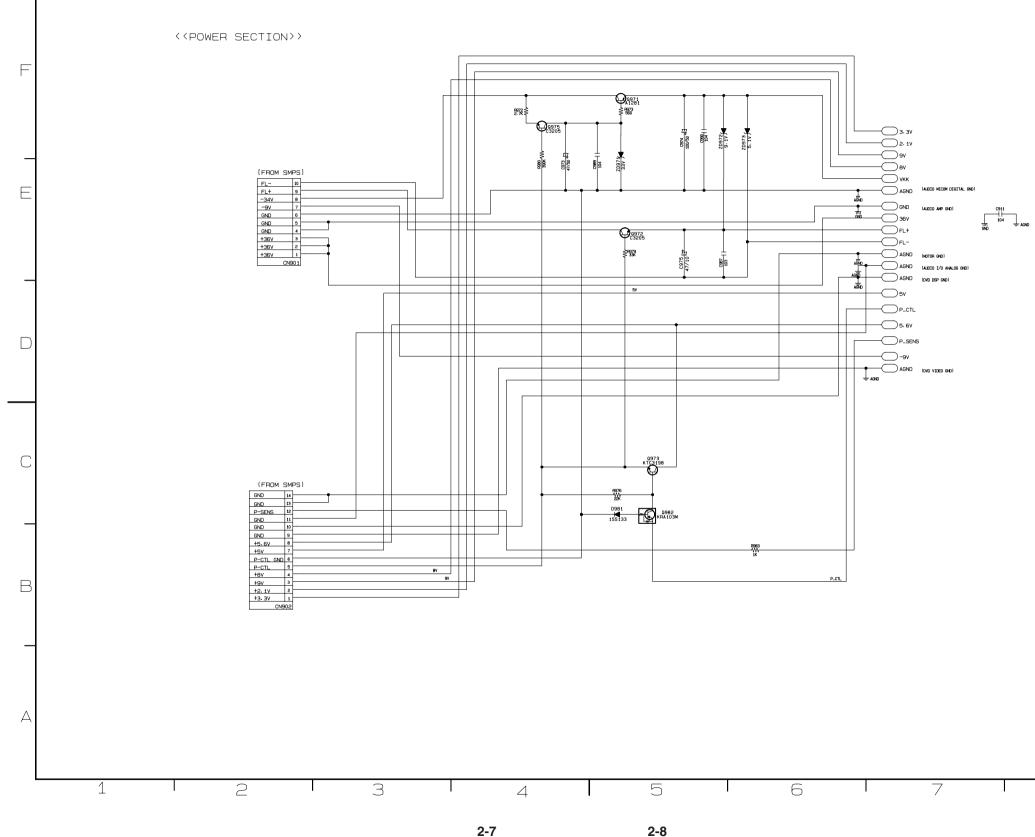


□ BLOCK DIAGRAM



□ SCHEMATIC DIAGRAMS

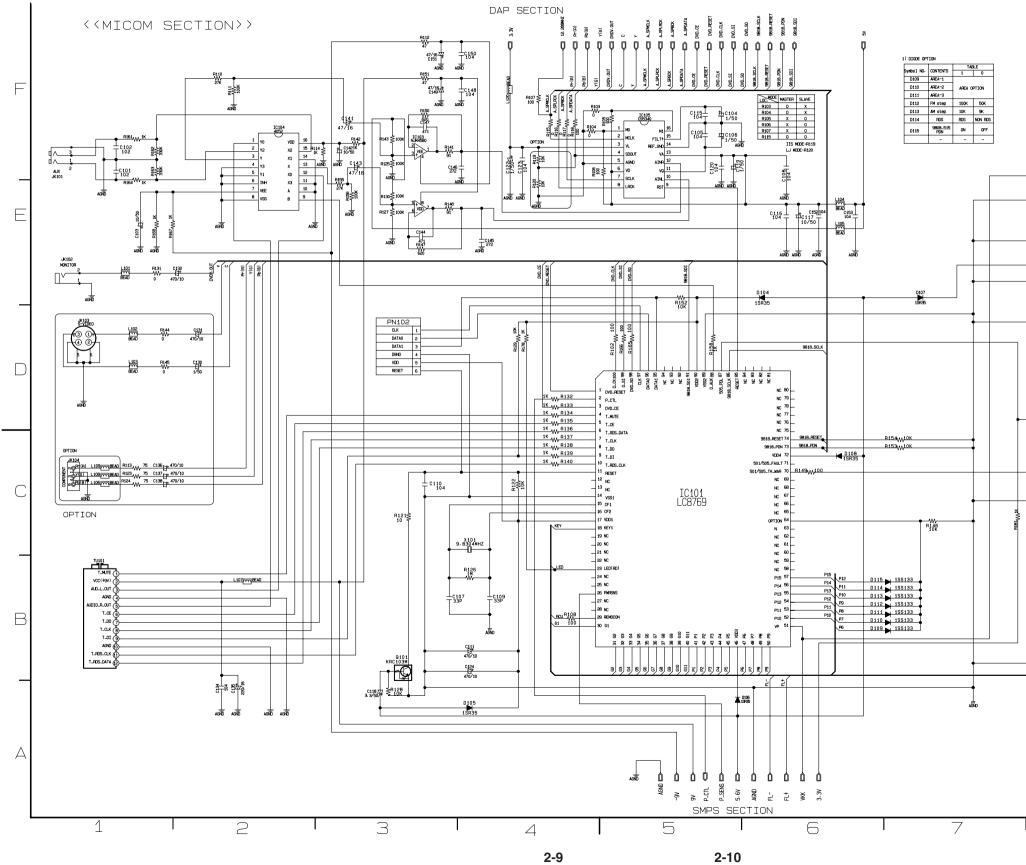
• POWER SCHEMATIC DIAGRAM



SCHEMATIC DIAGRAM (POWER) LH-T6340 3854R16345B

8

• MICOM SCHEMATIC DIAGRAM



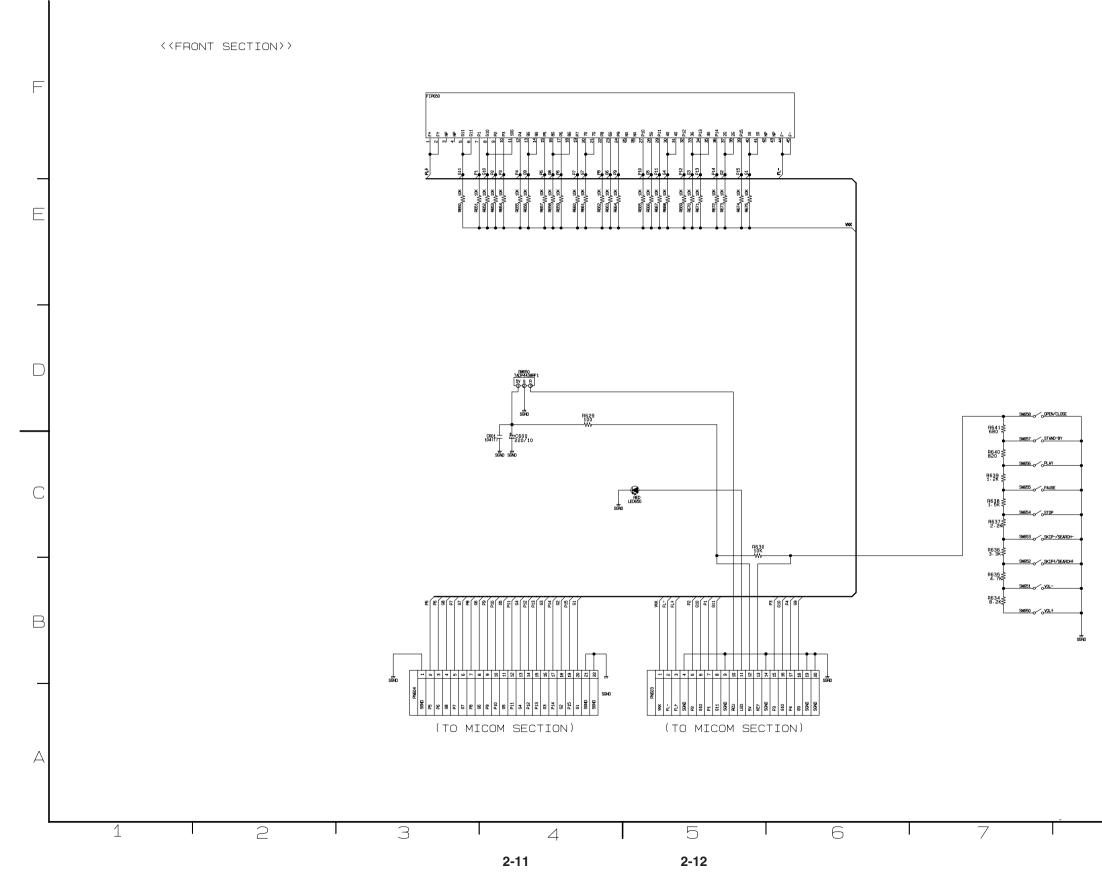
SCHEMATIC DIAGRAM(MICOM) LH-T6340 3854R16345D

	IO FH	
NFL-	- 1	WKK
FL+	- 2	FL-
111	- 3	FL+
	- 4	SGND
P2	- 5	P2
610	6	610
P1	- 7	P1
611	- 8	611
ROU	- 9	SGND
LED	10	RCU
(cub	11	LED
		5V
KEY	13	KEY
	14	SGND
P3	15	P3
G10	16	610
P4	17	P4
69	18	69
·		
1	19	SGND
L L		SGND
		PN103
		SECTION ≥ 505_PDN
		≥ 505_PON
		> 505_PON □ 505_TH_N ONT SECTIO SGND
e و		> 505_P0N 3 505_TH_N 0NT SECTIO 30ND 95
P6		> 505_PON □ 505_TH_N ONT SECTIO SGND
Рб 68		> 505_P0N 3 505_TH_N 0NT SECTIO 30ND 95
P6 68 P7	T0 FR	505_P0N 505_TH_N 505_TH_N
Рб 68	T0 FR	505_PON 505_TH_N 505_TH_N 505_TH_N 500 75 76 76 7 7
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AREA OPTION					
90010	D001	D005	D003		
KOREA	0	0	0		
USA	1	0	0		
EUROPE1	0	1	0		
SAC	1	1	0		
EUROPE2	0	0	1		
S-AFRICA	1	0	1		
JAPAN	0	1	1		
EUROPE3	1	1	1		
	1:USE 0:NOT USE				

TO FRONT SECTION

• FRONT SCHEMATIC DIAGRAM

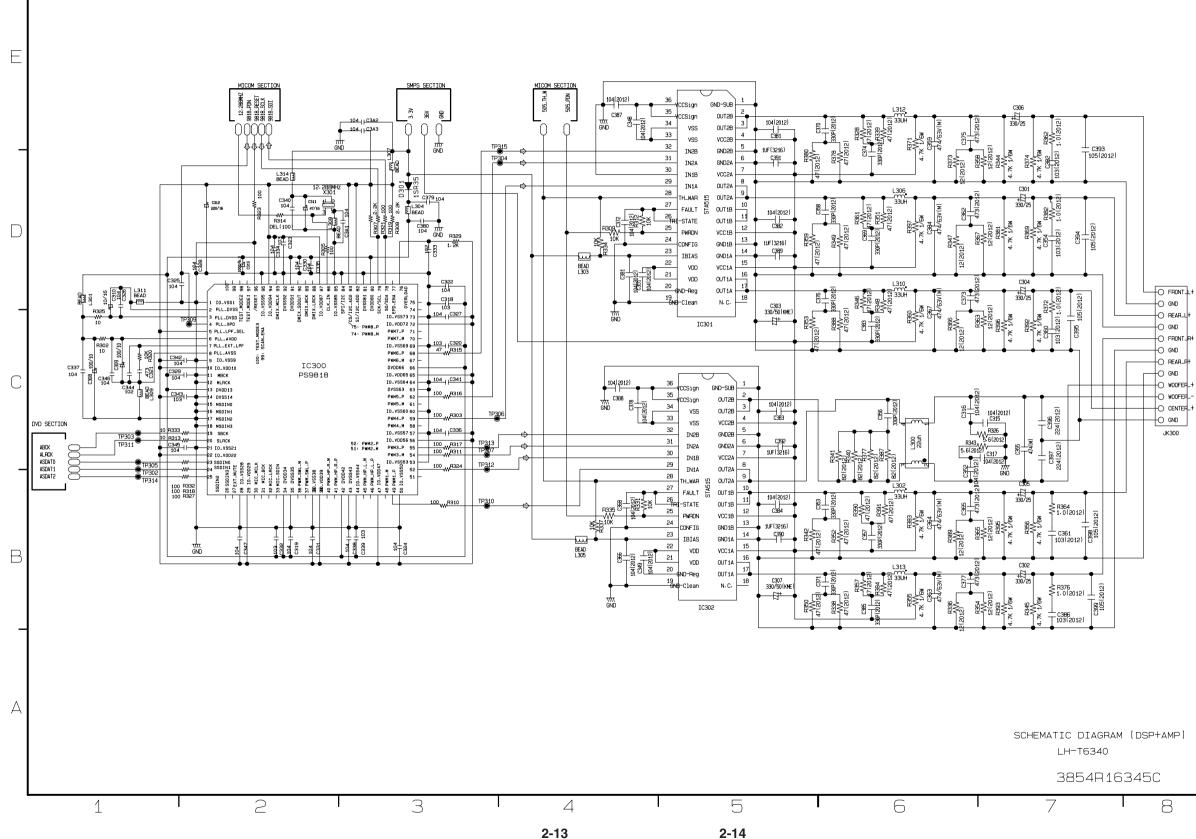


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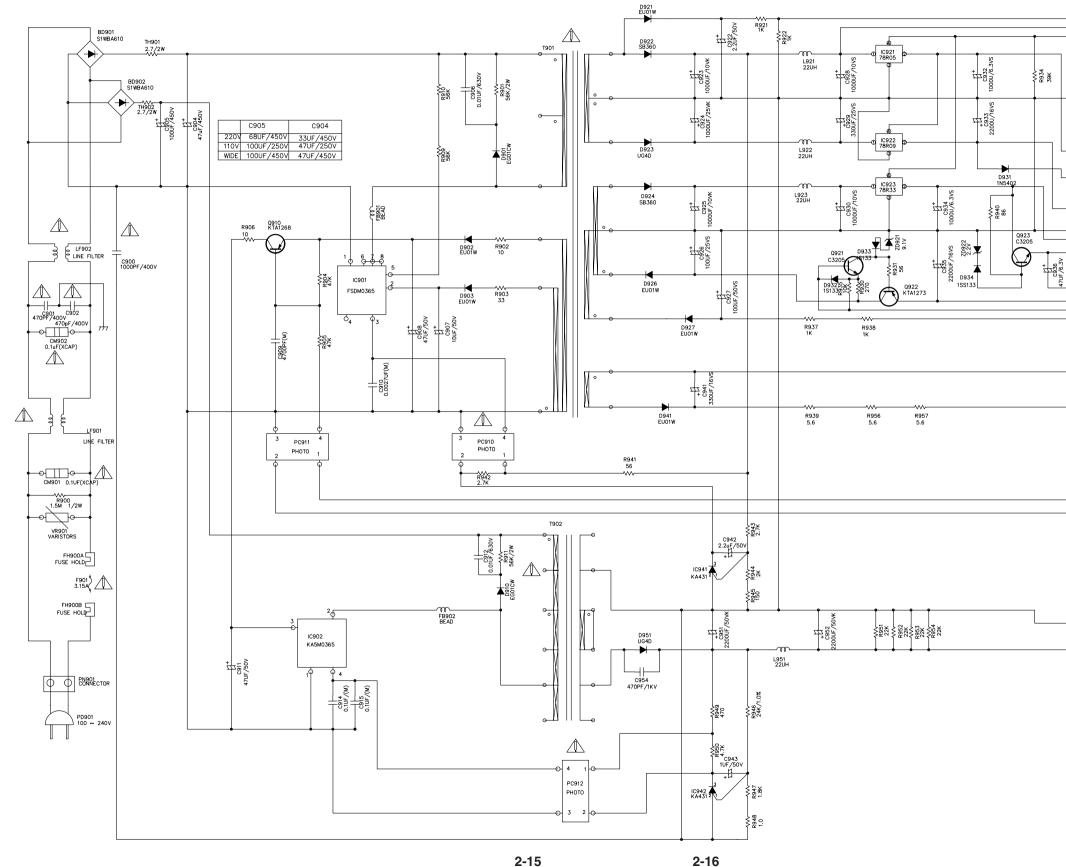
3854R16345J

FRONT(SCHEMATIC) LH-T6340

DSP& SCHEMATIC DIAGRAM



• SMPS-NARROW&WIDE SCHEMATIC DIAGRAM



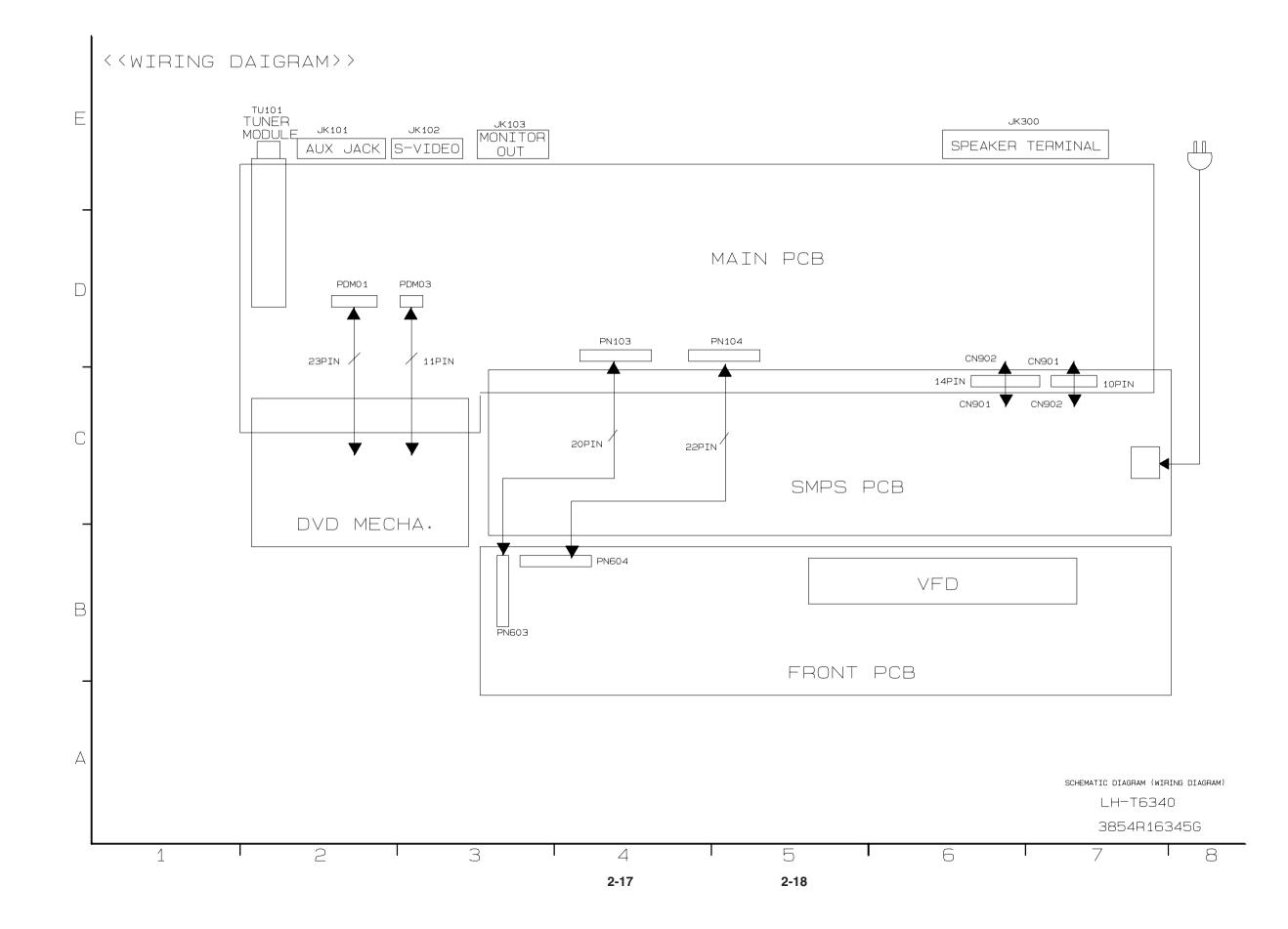
14 GND 13 GND 12 P-SEN 11 GND 10 GND 9 GN⁺ R932 270K 9 GND 9 GND 8 5.6V CPU 7 +5V 6 P-CON GND c P-CON UPO 5 P-CONTROL 4 +8V 3 +9V 2 +2.1V 1 +3.3V CN901 MV R933 560 FL-FL+ -34V -9V GND GND GND +36V +36V 2 + 1 + CN902← +36V

D929

155133

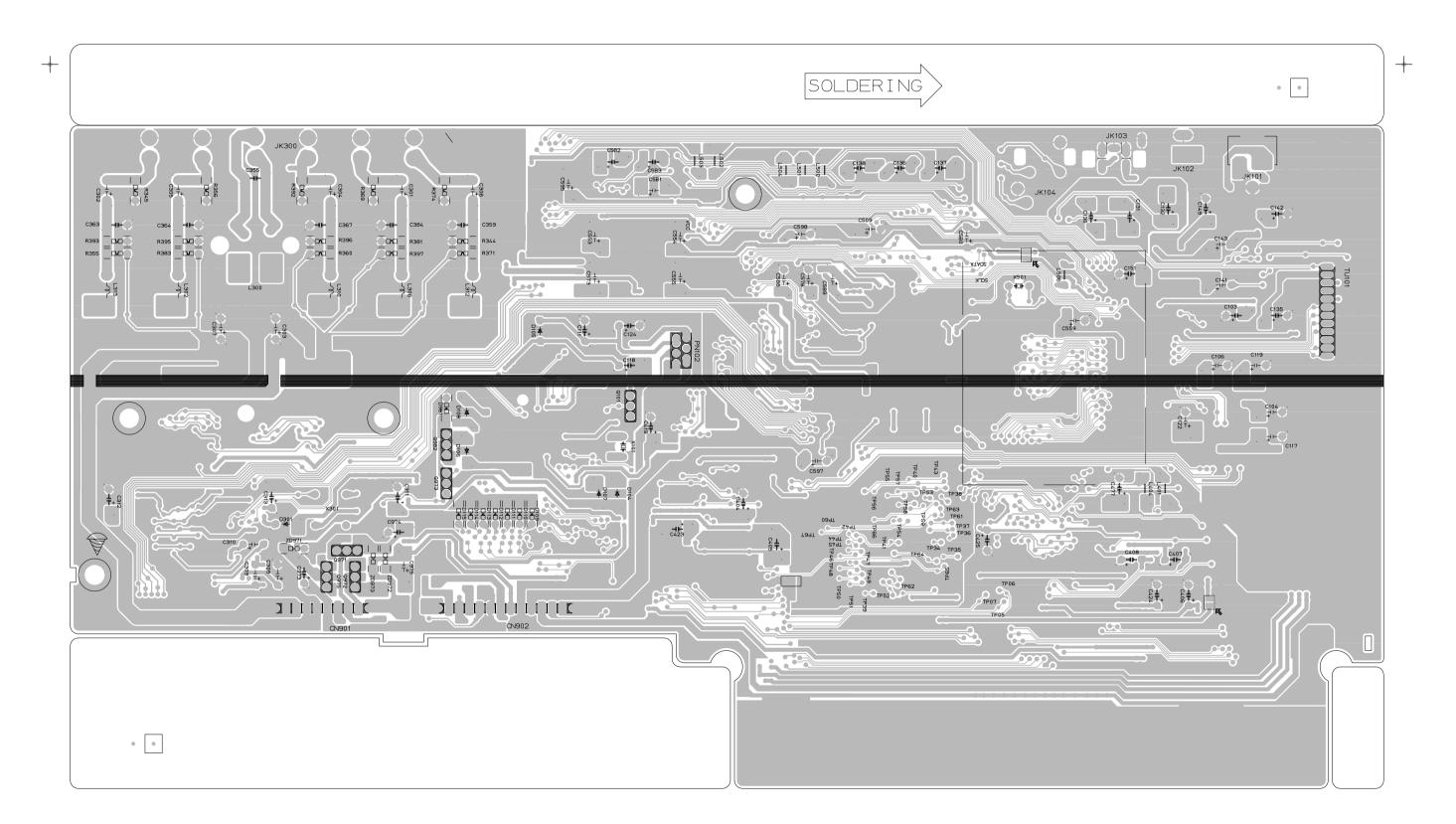
SMPS-NARROW&WDE LH-T6340 VD 3854R16340A

U WIRING DIAGRAM

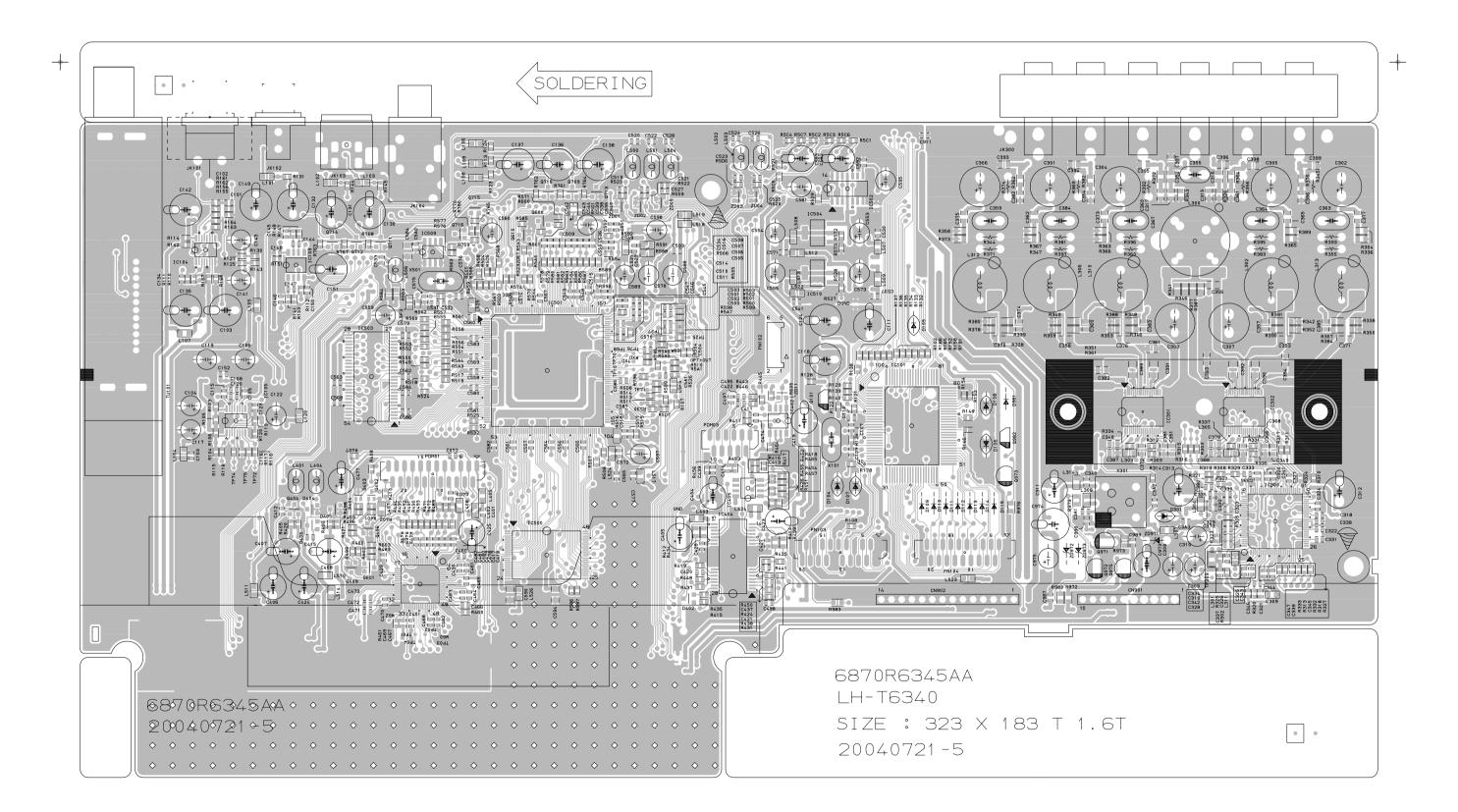


□ PRINTED CIRCUIT BOARD DIAGRAMS

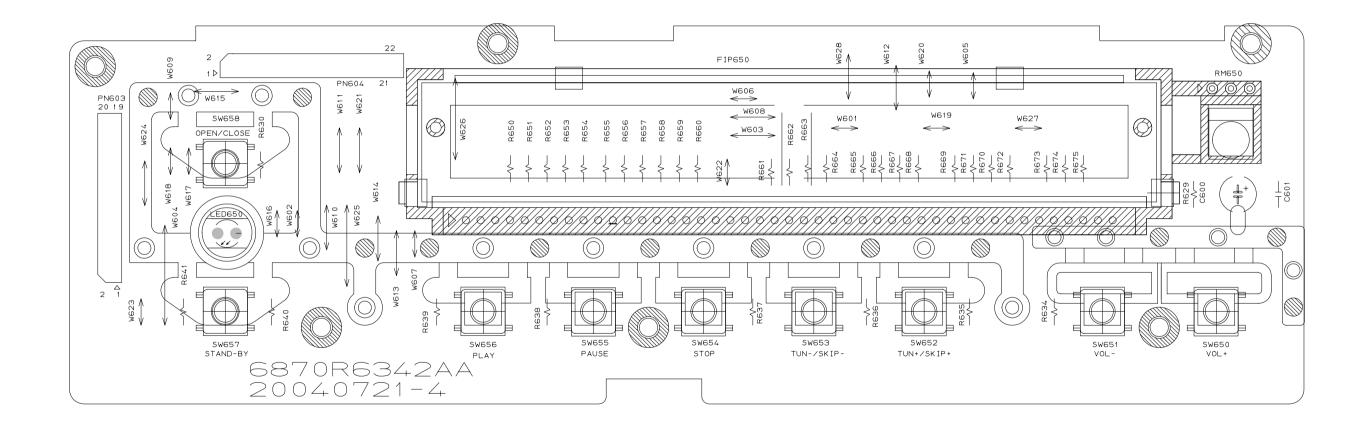
• MAIN/DVD P.C. BOARD DIAGRAM (BOTTOM)



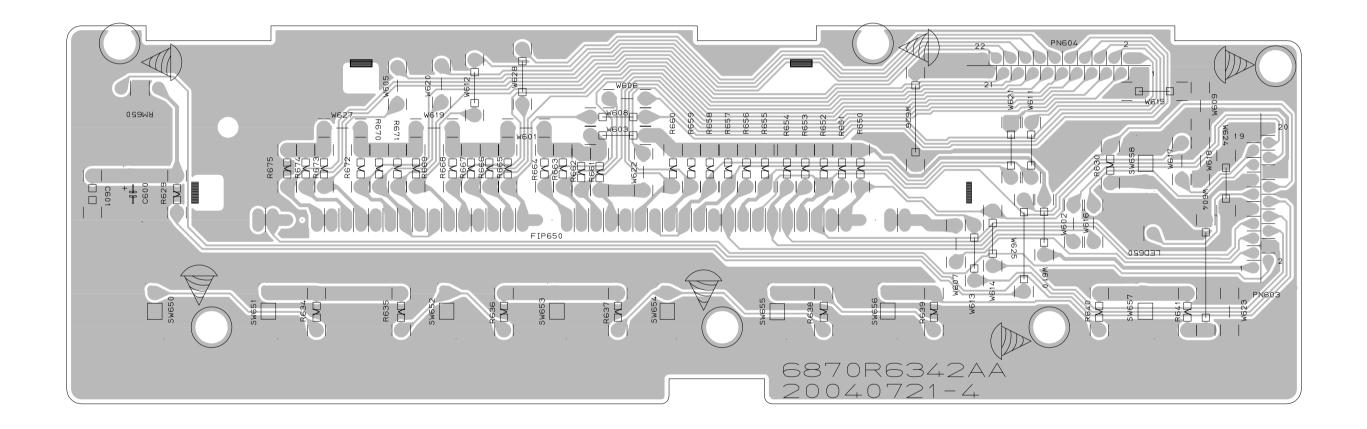
• MAIN/DVD P.C. BOARD DIAGRAM (TOP)

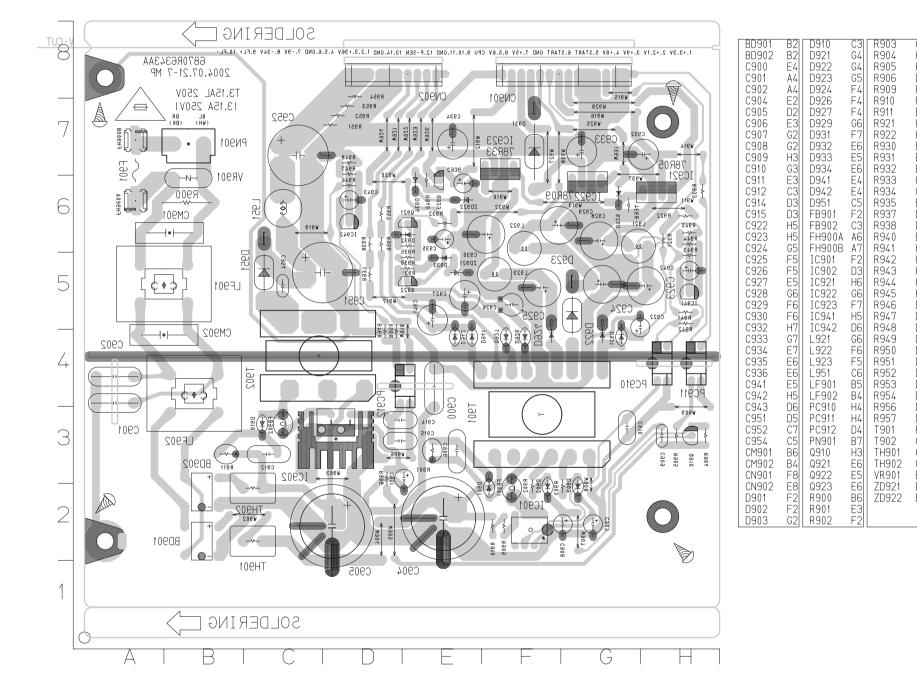


• FRONT P.C. BOARD (BOTTOM)



• FRONT P.C. BOARD (TOP)





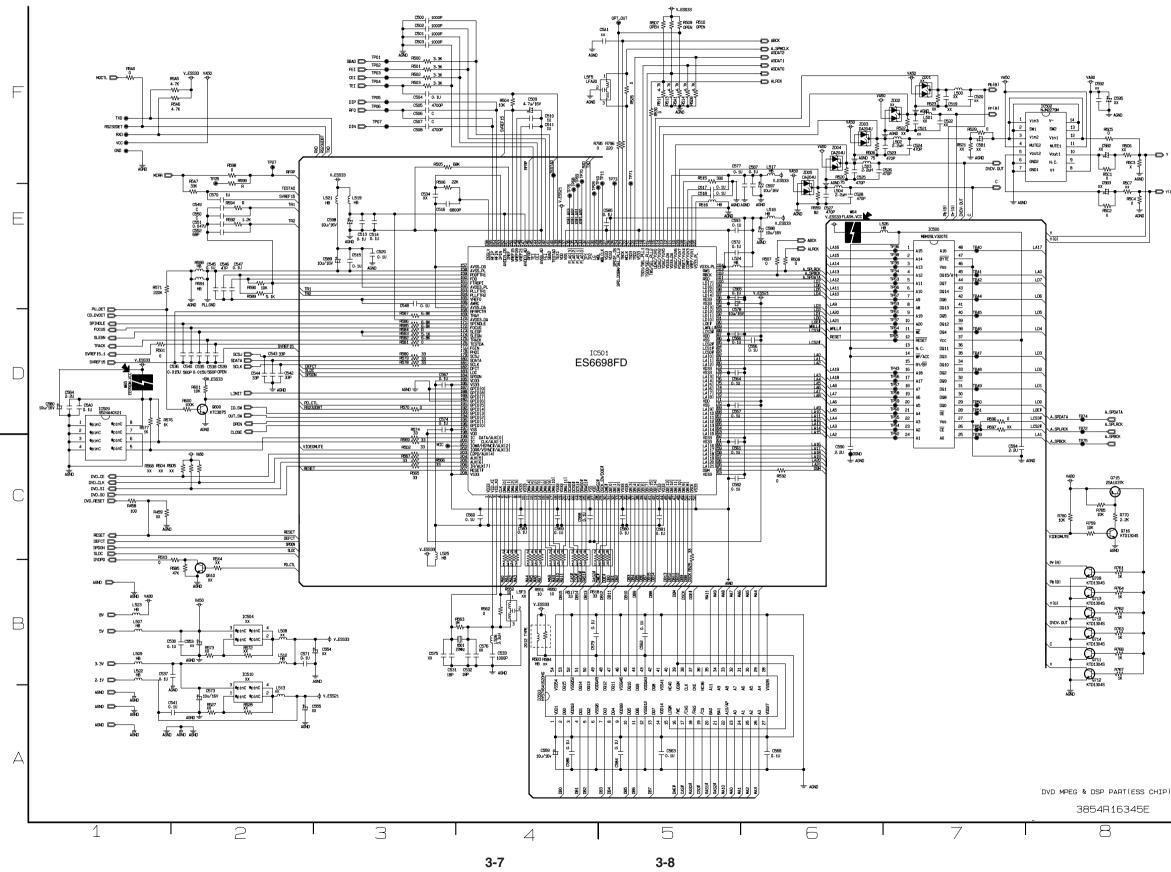
2-27

2-28

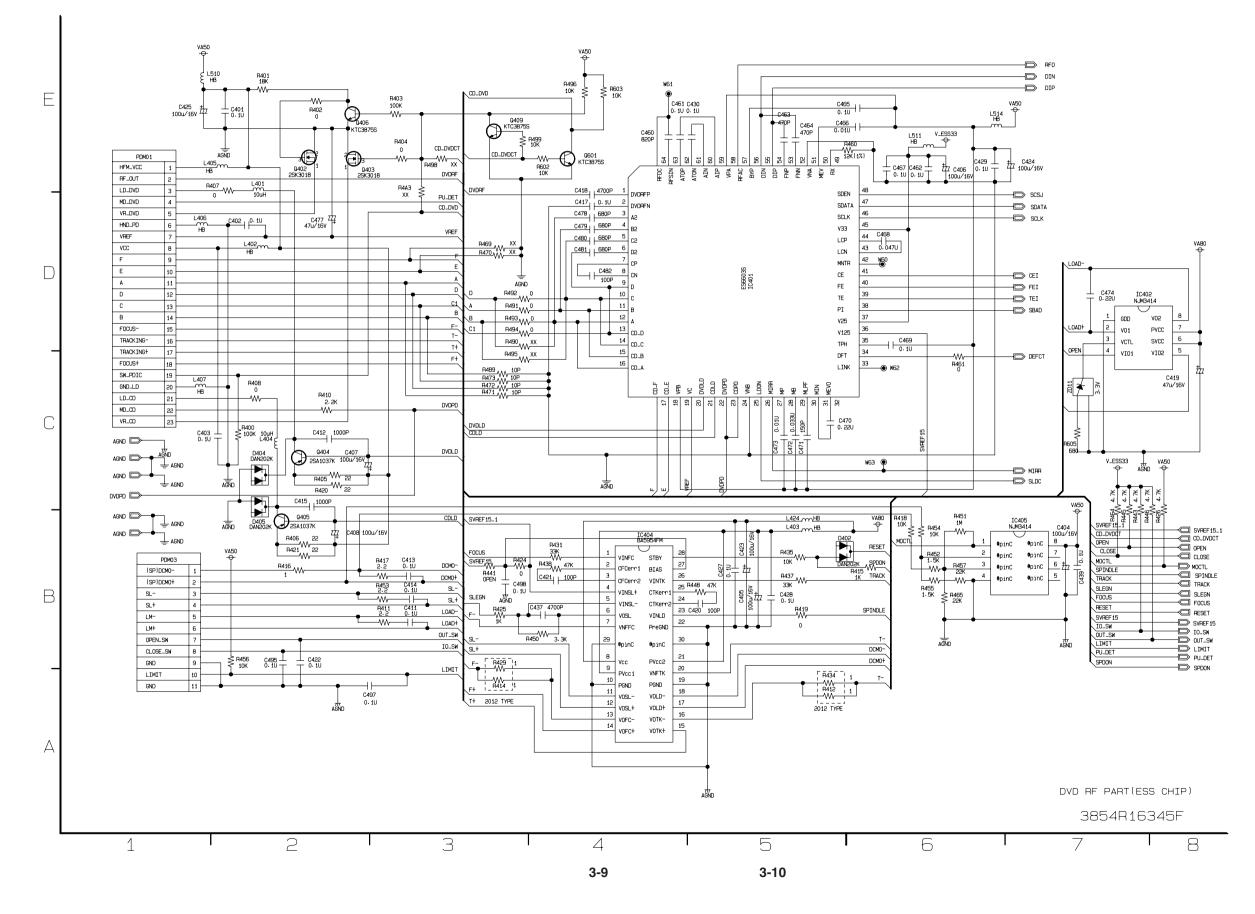
G13322236665566666555556666777444777786666342226656

DVD SCHEMATIC DIAGRAMS

• DVD MPEG & DSP SCHEMATIC DIAGRAM

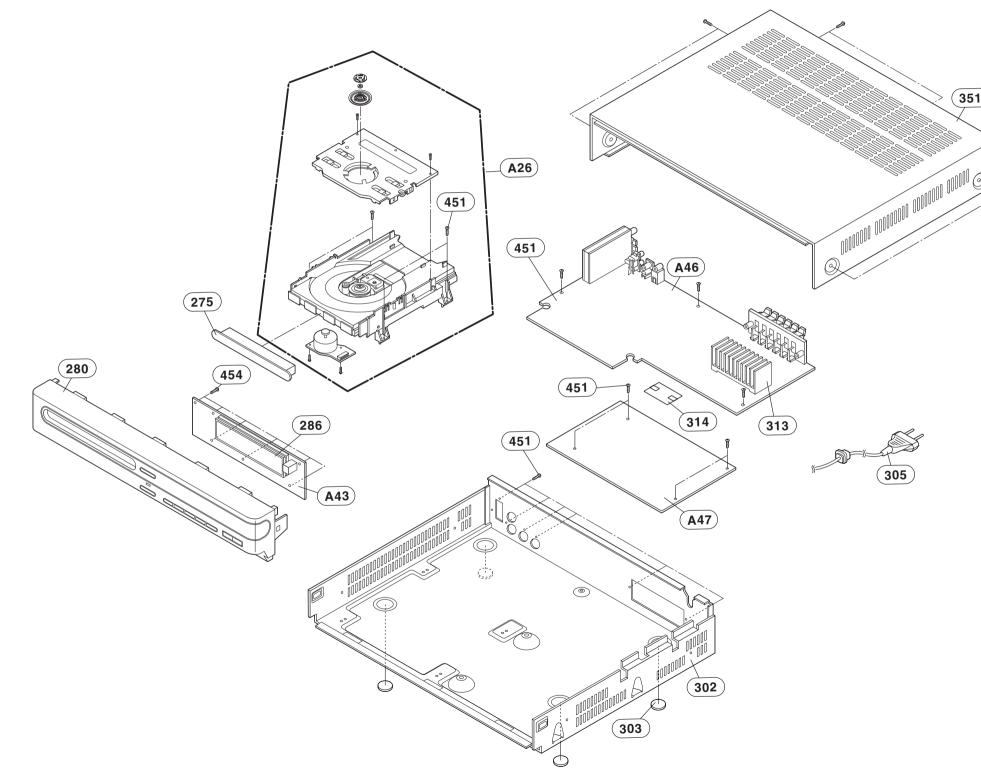


• DVD RF SCHEMATIC DIAGRAM



SECTION 4. EXPLODED VIEWS

□ CABINET AND MAIN FRAME SECTION



4-1



• DECK MECHANISM EXPLODED VIEW

